Loctite® 3566 Rapid Flow Low Profile Underfill

Category : Polymer , Adhesive , Thermoset

Material Notes:

COB/DCA Encapsulants are essential to the reliability of flip chip assemblies because they minimize the thermal mismatch between the flip chip and substrate.Loctite® Underfills and Encapsulants improve assembly operations by providing superior reliability and faster throughput. Improved reliability is achieved through products that have a high Tg, low CTE, high throughput and excellent adhesion. Faster throughput and higher yields are achieved through faster flow characteristics and increased cure speeds.Loctite® 3566 Rapid Flow Low Profile UnderfillAn extremely fast flowing, rapid cure underfill for industrial and consumer flip chip applications. Withstands operating temperatures up to 125°C.

Order this product through the following link:
http://www.lookpolymers.com/polymer_Loctite-3566-Rapid-FlowLow-Profile-Underfill.php

Physical Properties	Metric	English	Comments
Density	1.25 g/cc	0.0452 lb/in³	
Viscosity	4500 cP	4500 cP	Haake cone and plate rheometer @ 5/sec (35mm/2° cone)

Mechanical Properties	Metric	English	Comments
Tensile Modulus	2.07 GPa	300 ksi	

Thermal Properties	Metric	English	Comments
CTE, linear	50.0 µm/m-°C @Temperature 20.0 °C	27.8 µin/in-°F @Temperature 68.0 °F	
Glass Transition Temp, Tg	135 °C	275 °F	

Processing Properties	Metric	English	Comments
Cure Time	5.00 min @Temperature 150 °C	0.0833 hour @Temperature 302 °F	
Shelf Life	3.00 Month @Temperature -40.0 °C	3.00 Month @Temperature -40.0 °F	

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